



A Product Line of **Diodes Incorporated**

DMN4027SSD

40V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability

Case Material: Molded Plastic, "Green" Molding Compound. UL

Terminals: Finish - Matte Tin annealed over Copper lead frame.

Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.074 grams (approximate)

Terminals Connections: See diagram below

Solderable per MIL-STD-202, Method 208 @3)

Features and Benefits

Low on-resistance Fast switching speed

Mechanical Data

Case: SO-8

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Product Summary

V _{(BR)DSS}	R _{DS(on)} Max	Ι _D T _A = +25°C
40V	$27m\Omega @ V_{GS} = 10V$	7.1A
	$47 \mathrm{m}\Omega @ \mathrm{V}_{\mathrm{GS}} = 4.5 \mathrm{V}$	5.4A

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

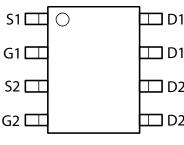
Applications

- Motor Control
- Backlighting
- **DC-DC Converters**
- **Power Management Functions**

SO-8

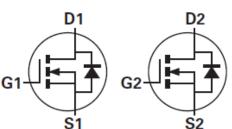


Top View



Top View

\Box D2 $\Box D2$



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMN4027SSD-13	Standard	SO-8	2500 / Tape & Reel
DMN4027SSDQ-13	Automotive	SO-8	2500 / Tape & Reel

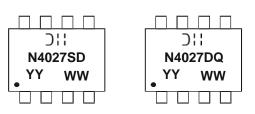
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information



☐:: = Manufacturer's Marking N4027SD = Product Type Marking Code for DMN4027SSD-13 N4027DQ = Product Type Marking Code for DMN4027SSDQ-13 YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01-53)





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	40	V
Gate-Source Voltage		(Note 5)	V _{GS}	±20	V
Continuous Drain Current V _{GS} = 10V	(Notes 7)		7.1		
	$V_{GS} = 10V$	$T_A = +70^{\circ}C$ (Notes 7)	I _D	5.7	А
		(Notes 6)		5.4	
Pulsed Drain Current	$V_{GS} = 10V$	(Notes 8)	I _{DM}	28.0	А
Continuous Source Current	(Body diode)	(Notes 7)	IS	3.3	А
Pulsed Source Current (Bod	y diode)	(Notes 8)	I _{SM}	28.0	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 6 & 9)		1.25 10.0		
Power Dissipation Linear Derating Factor	(Notes 6 & 10)	P _D	1.8 14.3	W mW/°C	
	(Notes 7 & 9)		2.14 17.2		
Thermal Resistance, Junction to Ambient	(Notes 6 & 9)		100		
	(Notes 6 & 10)	R _{0JA}	70	20.00	
	(Notes 7 & 9)		58	°C/W	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	R _θ JL	53		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

5. AEC-Q101 V_{GS} maximum is $\pm 16V.$ Notes:

6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

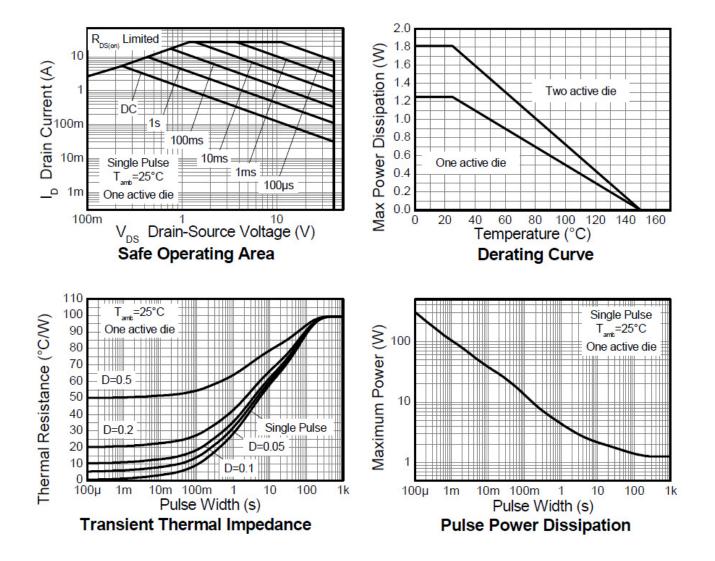
7. Same as note (3), except the device is measured at t \leq 10 sec.

8. Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300 μ s. The pulse current is limited by the maximum junction temperature. 9. For a dual device with one active die.

For a device with two active die running at equal power.
Thermal resistance from junction to solder-point (at the end of the drain lead).



Thermal Characteristics





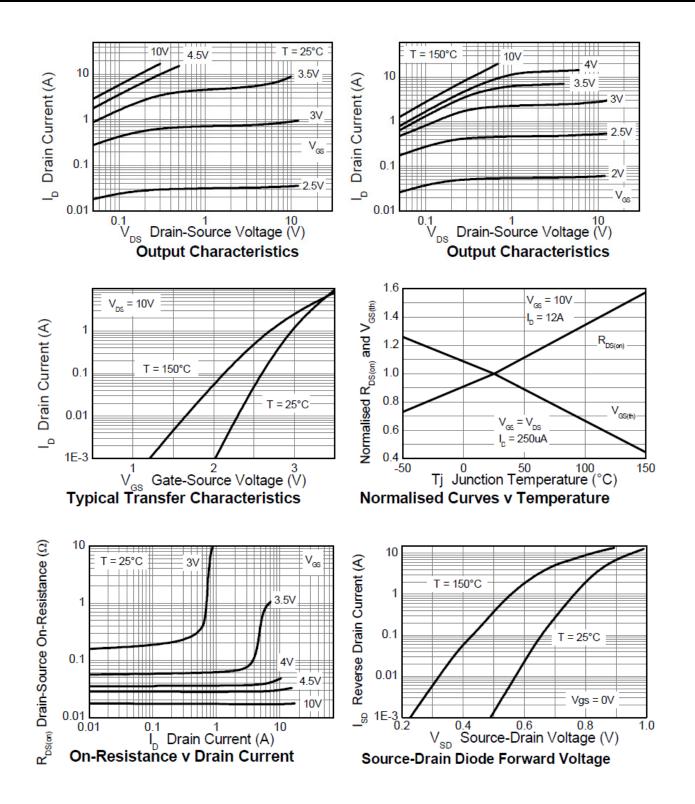


Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition
OFF CHARACTERISTICS	CjC		.,,		•		
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	—	V	$I_{D} = 250 \mu A, V_{G}$	s = 0V
Zero Gate Voltage Drain Current	I _{DSS}	_		0.5	μA	$V_{DS} = 40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_		±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	$I_D = 250 \mu A, V_D$	s = V _{GS}
Static Drain-Source On-Resistance (Note 12)	D		0.017	0.027	Ω	$V_{GS} = 10V, I_D = 7A$	
	R _{DS(ON)}	_	0.031	0.047	Ω	$V_{GS} = 4.5V, I_D = 6A$	
Forward Transconductance (Notes 12 & 13)	g fs	_	22.8	_	S	V _{DS} = 15V, I _D = 7A	
Diode Forward Voltage (Note 12)	V _{SD}	_	0.86	1.1	V	$I_S = 7A, V_{GS} = 0V$	
Reverse recovery time (Note 13)	t _{rr}		12.1	_	ns	I _S = 2.1A, di/dt = 100A/µs	
Reverse recovery charge (Note 13)	Q _{rr}	_	5.1	_	nC		
DYNAMIC CHARACTERISTICS (Note 13)							
Input Capacitance	C _{iss}		604	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz	
Output Capacitance	C _{oss}	_	106	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	59.6	_	pF		
Total Gate Charge (Note 14)	Qg	_	6.3	_	nC	$V_{GS} = 4.5V$	
Total Gate Charge Note 14)	Qg	_	12.9	_	nC		$V_{DS} = 20V$ $I_D = 7A$
Gate-Source Charge Note 14)	Q _{gs}	_	2.4	_	nC	$V_{GS} = 10V$	
Gate-Drain Charge Note 14)	Q _{gd}	_	3.3	_	nC		
Turn-On Delay Time Note 14)	t _{D(on)}		3.1	_	ns	$V_{DD} = 20V, V_{GS} = 10V$ $I_D = 1A, R_G \cong 6.0\Omega$	
Turn-On Rise Time Note 14)	tr	_	3.1	—	ns		
Turn-Off Delay Time (Note 14)	t _{D(off)}	_	15.4	_	ns		
Turn-Off Fall Time Note 14)	tf		7.5	_	ns		

12. Measured under pulsed conditions. Pulse width \leq 300µs; duty cycle \leq 2%. 13. For design aid only, not subject to production testing. 14. Switching characteristics are independent of operating junction temperatures. Notes:

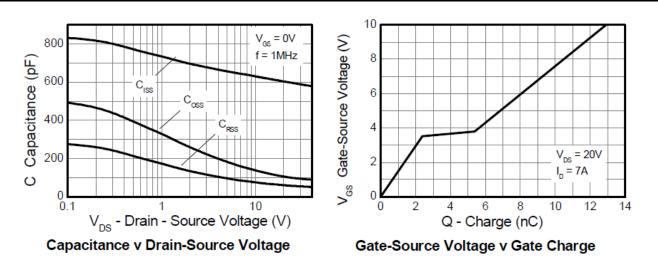


Typical Characteristics

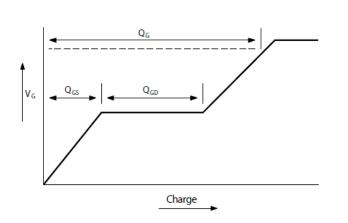




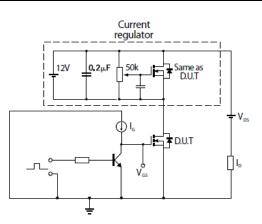
Typical Characteristics (cont.)



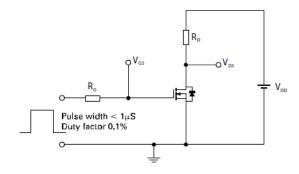
Test Circuits



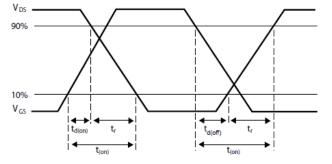
Basic gate charge waveform



Gate charge test circuit



Switching time test circuit

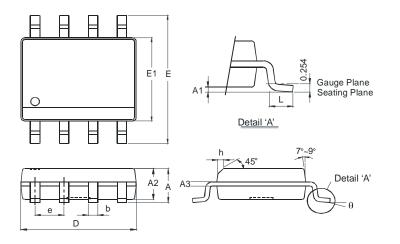


Switching time waveforms



Package Outline Dimensions

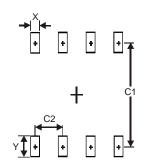
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



1						
	SO-8					
Dim	Min	Max				
Α	-	1.75				
A1	0.10	0.20				
A2	1.30	1.50				
A3	0.15	0.25				
b	0.3	0.5				
D	4.85	4.95				
Е	5.90	6.10				
E1	3.85	3.95				
е	1.27	Тур				
h	-	0.35				
L	0.62	0.82				
θ	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



DMN4027SSD

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